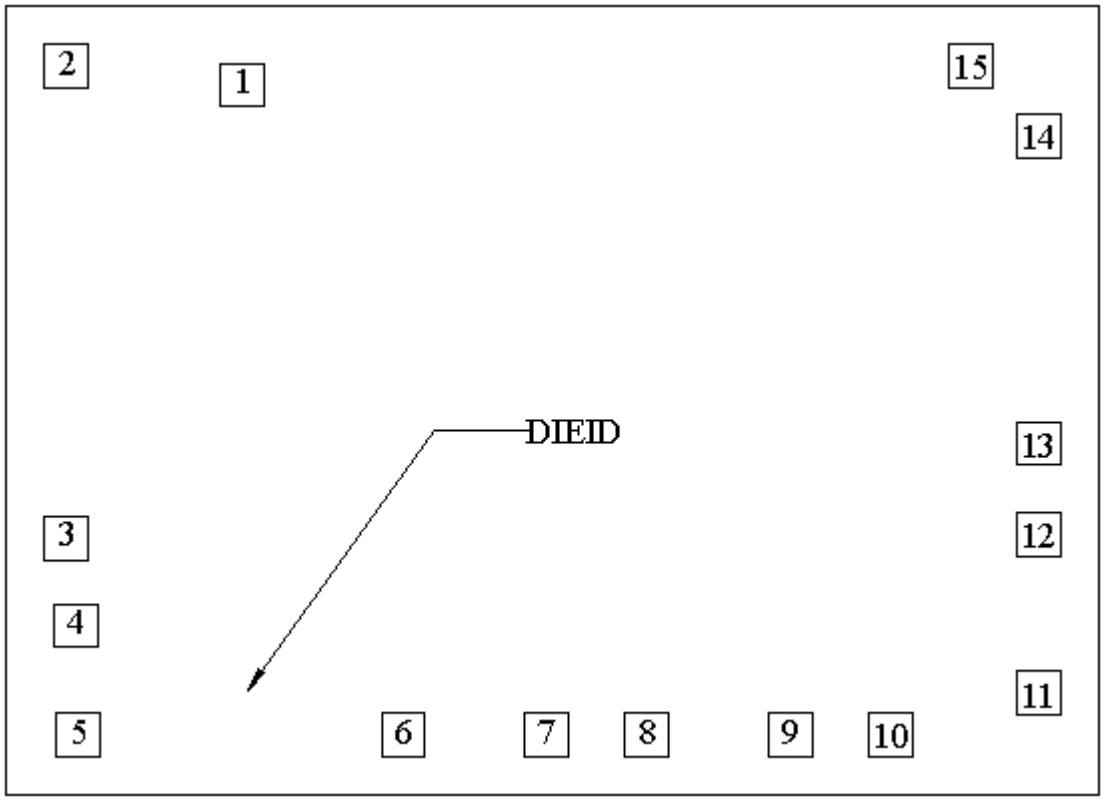
DAC0808 MDC MWC
8-BIT DIGITAL-TO-ANALOG CONVERTERS

December 11,2006

DIE LAYOUT (B -STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	DAC1408LB	Bond Pad Opening Size (min)	91µm x 89µm
Die Step	B	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	2286µm x 1651µm 90.0mils x 65.0mils	Back Side Connection	Floating
Thickness	406µm Nominal		
Min Pitch	146µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (B -Step)

(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
GND	1	-648	660	91	x	91
VEE	2	-1016	699	91	x	91
IO	3	-1016	-287	91	x	91
AI (MSB)	4	-996	-470	91	x	91
A2	5	-991	-699	91	x	91
A3	6	-312	-699	91	x	91
A4	7	-13	-699	91	x	91
A5	8	198	-699	91	x	91
A6	9	498	-699	91	x	91
A7	10	709	-699	91	x	91
A8 LSB	11	1016	-612	91	x	91
VCC	12	1016	-279	91	x	91
VREF +	13	1016	-89	91	x	91
VREF -	14	1016	554	91	x	91
COMPENSATION	15	876	700	91	x	89

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